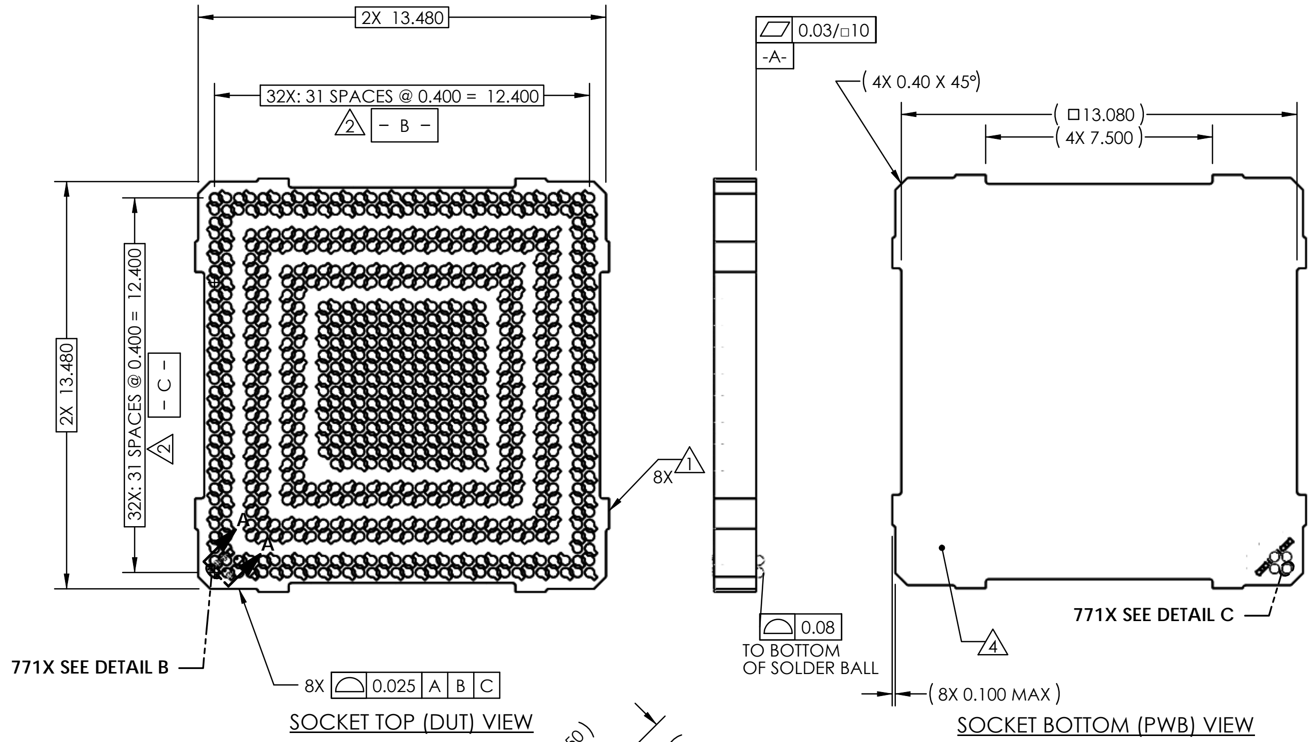
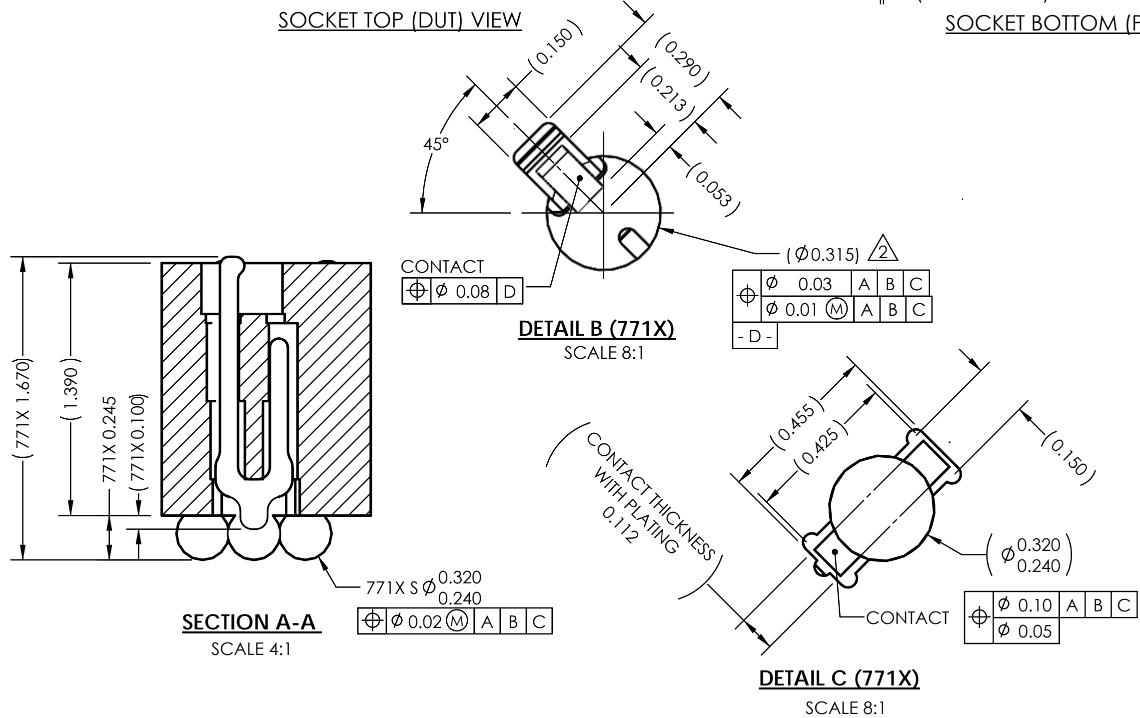
| REV | ECO | BY | DESCRIPTION | APV | DATE |
|---|---|---|---|---|---|
| A | 30015 | EJT | Initial Design | MP | 12/04/09 |




Notes:

1. Tooling marks permitted. Maximum 0.10 protrusion (shown)
2. Dimension locates center of contact/slot.
3. Socket designed for Qualcomm package as defined on package outline drawing (POD) NT90-VN165-2 revision B.
4. Most slots not shown for clarity and file size.
5. Reference Cascade Microtech specification 103862-0004 for solder attachment.
6. Reference Cascade Microtech specification 103863-0001 for application notes.




Parts List

| Item | QTY. | Part Number | Description | Material |
|---|---|---|---|---|
| 0 | - | 107140-0007 | SOCKET, 771G4013.4-0.40 | - |
| 0 | - | 103864-0097 | PRESS, DEVICE INSERT (SOLD SEPERATELY) | POLYCARBONATE |
| 0 | - | 105900-0004 | EXTRACTION TOOL, 4X53 (SOLD SEPERATELY) | TORLON 5030 |
| 0 | - | 104553-0142 | STENCIL, FLEX, 771GRYH13.4-0.40 (SOLD SEPERATELY) | CIRLEX |
| 1 | 1 | 107141-0007 | CS, 771G4013.4-0.40 | - |
| 1.1 | 1 | 107143-0007 | HSG, 771G4013.4-0.40 | CIRLEX |
| 1.2 | 771 | 104468-0014 | CONTACT, GRY, HALF, ø0.25 | BeCu |
| 2 | 771 | 106957-0001 | BALL, SOLDER, 10MIL DIA | SAC 305 |

UNLESS OTHERWISE SPECIFIED
- DIMENSIONS ARE IN MILLIMETERS
- DIM'S APPLY AFTER PLATING
TOLERANCES UNLESS OTHERWISE NOTED: ANGLES ±1° DECIMALS X.X ±0.25 X.XX ±0.10 X.XXX ±.050

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CAD GENERATED DRAWING
DO NOT MANUALLY UPDATE

DRAWING APPROVALS

| NAME | DATE |
|---|---|
| DRAWN E.Turin | 11/30/09 |
| APPVD M.Peery | 12/04/09 |

CASCADE MICROTECH
7115 NORTHLAND TERRACE SUITE 400
BROOKLYN PARK, MN 55428
(763) 509-0066

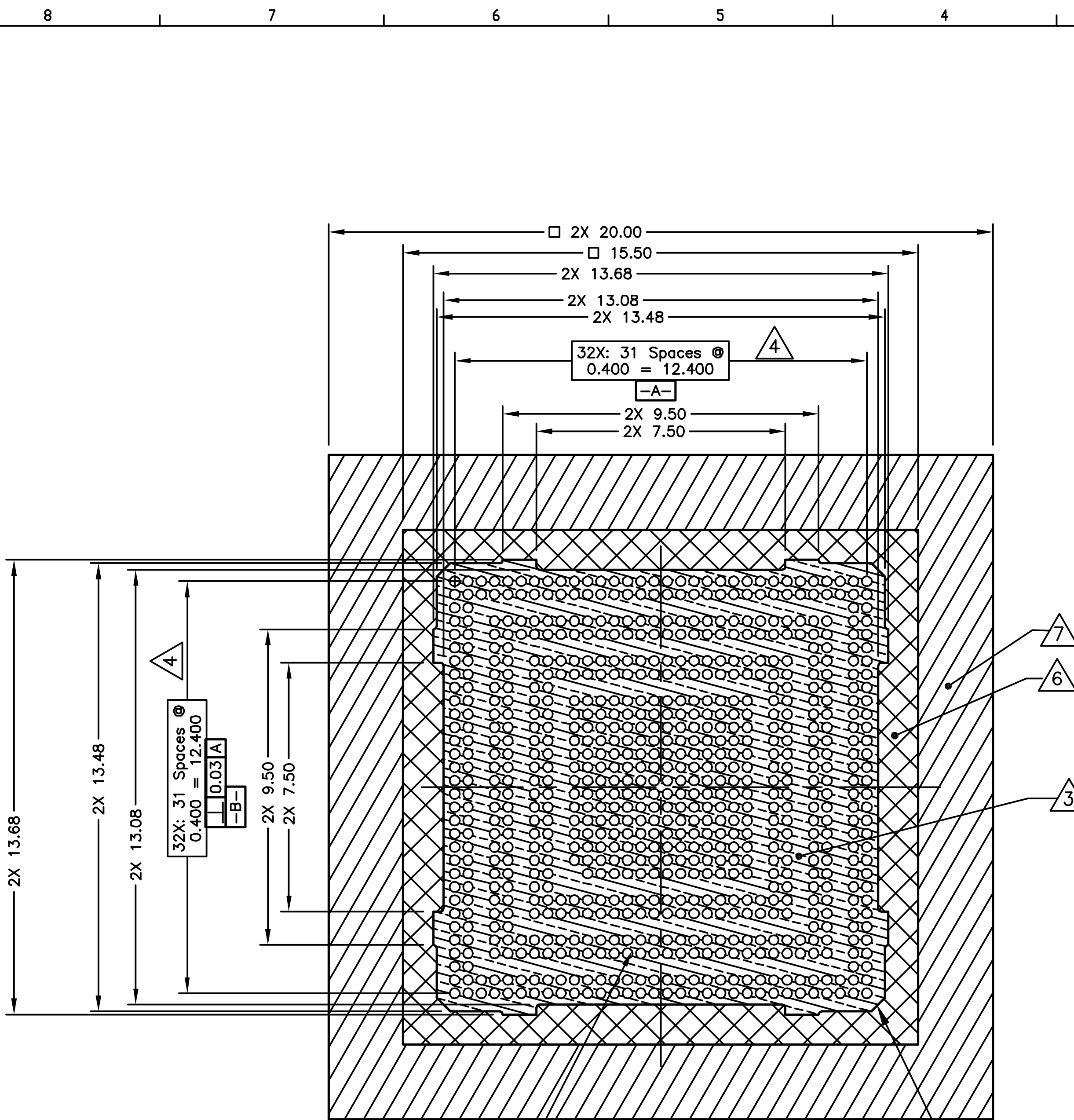
# SOCKET, 771G4013.4-0.40 W/SOLDER BALLS

LEGEND:
X NOTE CALLOUT
01 REVISION CHANGE
X ITEM NUMBER

THIRD ANGLE PROJECTION

SIZE: C | CAD FORMAT: SOLIDWORKS | DRAWING NO. 107140-0007 | REV. A

SCALE | MATERIAL: SEE BOM




NOTES:

1. Pad plated 100 micro inches solder minimum over copper base metal. Finished surface must be at same height as contact pad. Pads to flat (⏥ 0.03), free of burrs, solder mask, silk-screen, etc.
2. Unless otherwise noted, all features located ⌖ 0.10 A B
3. This surface to be flat with solder mask / silk-screen no more than 0.05 mm above the surface of the plated pads.
4. Locates center of pad/pattern.
5. The view shown is the top (connector side) of the board (looking through the connector).
6. Component placement area. Recommended no components. Please notify Cascade Microtech if unable to meet these recommendations.
7. Component placement area. Rcommended max height 0.70. Please notify Cascade Microtech if unable to meet these recommendations.

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- DIM'S APPLY AFTER PLATING

TOLERANCES UNLESS OTHERWISE NOTED:

| ANGLES | DECIMALS | |
|---|---|---|
| ±1° | X.XX | ±0.25 |
| | X.XX | ±0.10 |
| | X.XXX | ±0.050 |

LEGEND: △ NOTE CALLOUT; ⬡ REVISION CHANGE; ① ITEM NUMBER

CASCADE MICROTECH
7115 NORTHLAND TERRACE SUITE 400
BROOKLYN PARK, MN 55428
(763) 509-0066

TITLE: SCKT, 771G40 13.4-0.40 W/ SOLDER BALLS

| SIZE | CAD FORMAT | DRAWING NO. | REV. |
|---|---|---|---|
| C | AUTOCAD | 107140-0007 | A |

SCALE | MATERIAL | SHEET 2of2